产品规格承认书

SPECIFICATIONS

CUSTOMER:

客户:

产品名称:

	DESCRIPTION: 地磁天线						
	客户型号:	•					
		DT NO.					
		KI NU:					
	产品型号:						
	OUR MODEL N	0:	<u> </u>	<u>BX1608MA</u>	<u>)2</u>		
	日期:						
	DATE:						
矿	角认签字,盖章	后请返回	承认书-	一份			
	PLEASE RETU	RN TO US	ONE CO	PY OF "SPECI	FICATIO	N FOR APPROVA	L"
	WITCH VOLD A		O T ON I A MI	IDDG			
	WITH YOUR A	PPROVED	SIGNATU	RES			
				ingye Technology			
				O Science and Te Ighua District, Sh			
			, — — ·	9		,	
	核准		审核	刘飞	制作	刘小美	
	安亡	₽承认签₽	ÍΠ				
	合)	子 八 並 レ					
		日期					
UNLES:	S OTHER SPECIFI X.X=±	ED TOLERA X.XX=	NCES ON	ဥပ်	深圳市	前 開伴兴业科技系	
ANGL	$ES = \pm$	HOLEDIA	\ = ±	PENGBANXING			
SCALE:	N/A BY : Sera	UNIT: mm CHECKED B	Y: XD	TECHNOLOGY Lim	ited AND SHA	CATIONS ARE THE PROPE	OR USED AS
	D BY: Sera	APPROVED		THE BASIS FOR DEVICES WITHOUT		CTURE OR SALE OF AF	PARATUS OR
		.6		DOCUMENT		1 222	ODEO DEV
TITLE:	CHIP2450-1608 Sp	ecification		NO.		1608	SPEC REV.

PBX1608MA02 Specification

Operating Temp. : -40 ℃~+85 ℃

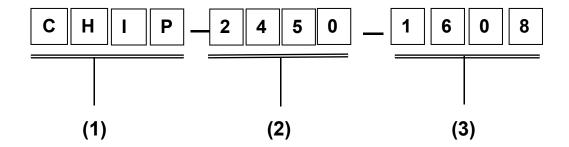
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

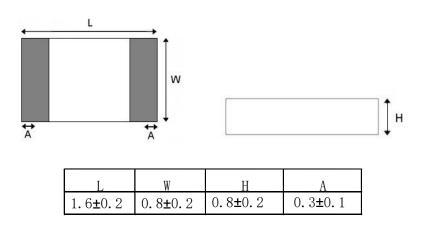
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



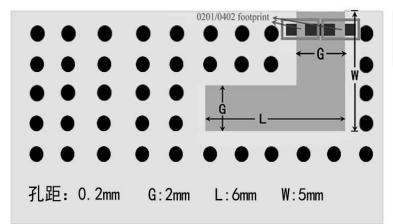
- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 1.6*0.8

4. SHAPE AND DIMENSIONS:

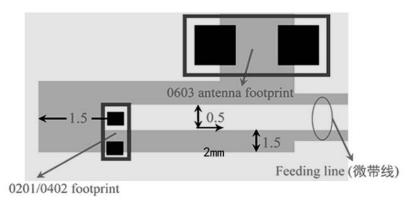


UNLESS OTHER SPECIF X=± X.X=± ANGLES = ±	TIED TOLERANCES ON: X.XX= HOLEDIA = ±	PENGBANXING	深圳市朋伴兴业科技有	i限公司
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PE		
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR US THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATU		
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.
TITLE: CHIP2450-1608 Specification		NO.	1000	P1

●天线位于 PCB 板内部或中间位置时(长条式耳机): (单位: mm)

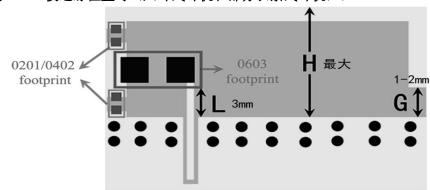






天线最优放置于中间区域,净空区周围最优需要至少一排过孔。

●天线位于 PCB 板边缘位置时(入耳式耳机和部分长条式耳机):

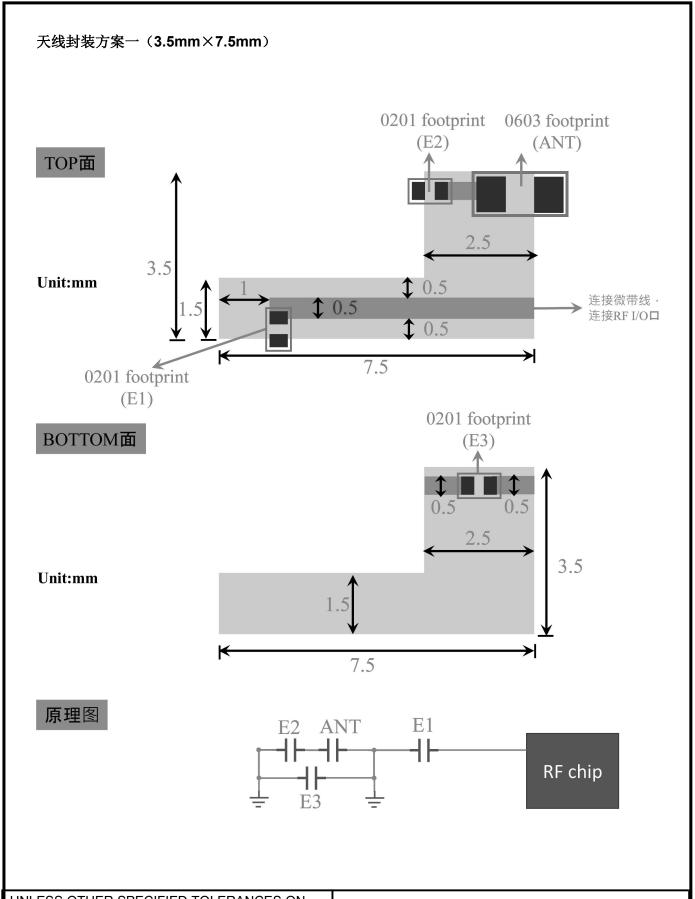


天线最优放置于 PCBA 的边缘; 天线及其走线设置在单层。

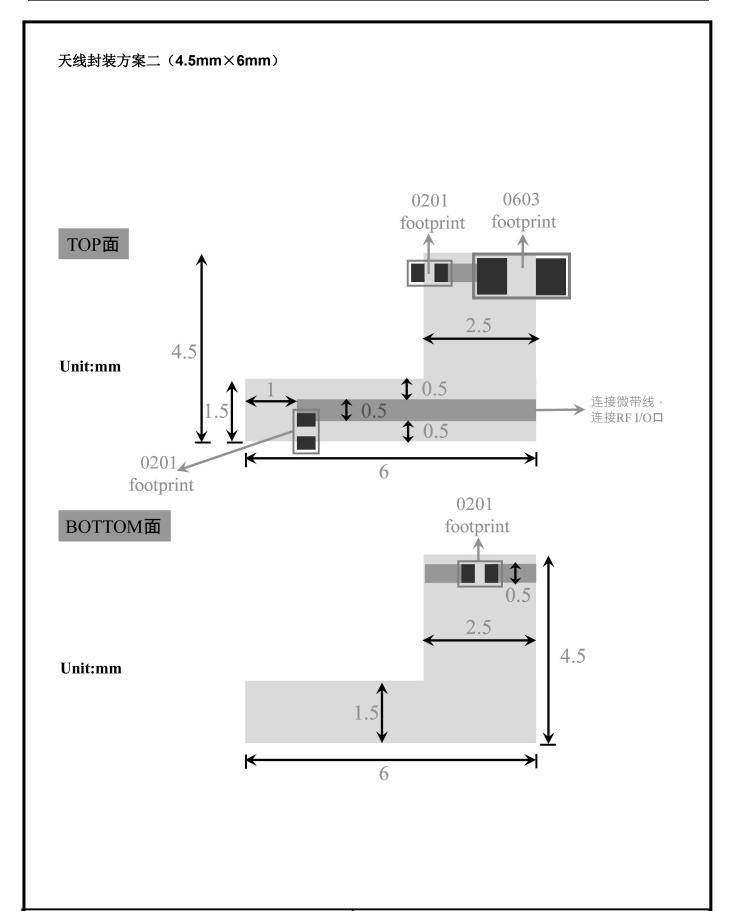
设计标准:

- 1. 图中的尺寸仅作为参考;实际尺寸会根据不同版型进行优化。
- 2. 净空区周围最优需要至少一排过孔, 孔径 0.3mm, 与 PCBA 上的其它回路或物料进行隔离。

UNLESS OTHER SPECIF	TIED TOLERANCES ON:	№ 深圳市朋伴兴业科技有际		78 /\ =1
$X=\pm$ $X.X=\pm$	X.XX =	and the same of th	深圳印册住兴业科技有	限公司
$ANGLES = \pm$	$HOLEDIA = \pm$	PENGBANXING		
SCALE: N/A	UNIT: mm		S AND SPECIFICATIONS ARE THE PROPER	
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited and shall not be reproduced or used A THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS O		
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOU	JT PERMISSION	
TITLE. CHIP2450-1608 S	necification	1 5000		SPEC REV.
TITLE: CHIP2450-1608 Specification		NO.	1000	P1



UNLESS OTHER SPECIFIED TOLERANCES ON:	№ 深圳市朋伴兴业科技有[78/3
$X=\pm$ $X.X=\pm$ $X.XX=$	and the same of th	深圳市朋伴兴业科技有	限公司
ANGLES = \pm HOLEDIA = \pm	PENGBANXING		
SCALE: N/A UNIT: mm		S AND SPECIFICATIONS ARE THE PROPER	
DRAWN BY : Sera CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED A THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS O		
DESIGNED BY: Sera APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE: CHIP2450-1608 Specification	DOCUMENT	1608	SPEC REV.
TITLE: Chir2430-1606 Specification	NO.	1000	P1

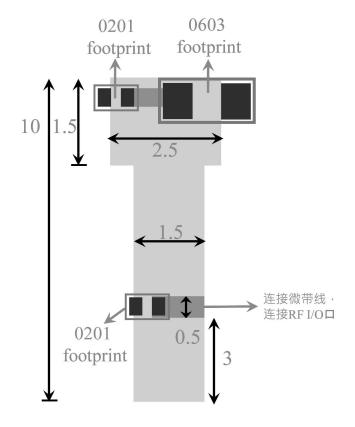


UNLESS OTHER SPECIFIED TOLERANCES ON: X=+ X.X=+ X.XX=	dg	№ 深圳市朋伴兴业科技有限		
ANGLES = \pm HOLEDIA = \pm	PENGBANXING			
SCALE: N/A UNIT: mm		S AND SPECIFICATIONS ARE THE PROPER	-	
DRAWN BY : Sera CHECKED BY: XD		TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED A THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS O		
DESIGNED BY: Sera APPROVED BY: XD	DEVICES WITHOU	DEVICES WITHOUT PERMISSION		
TITLE: CHIP2450-1608 Specification	DOCUMENT	1608	SPEC REV.	
TITLE: CHIP2430-1606 Specification	NO.	1008	P1	

天线封装方案三(1.5mm×10mm)

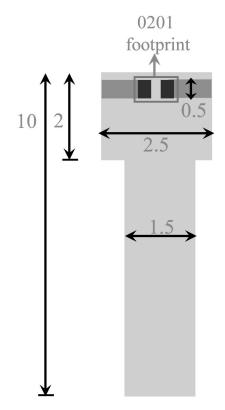
TOP面

Unit:mm



BOTTOM面

Unit:mm

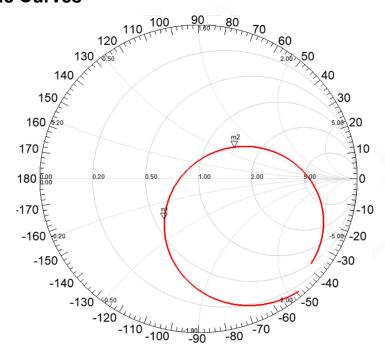


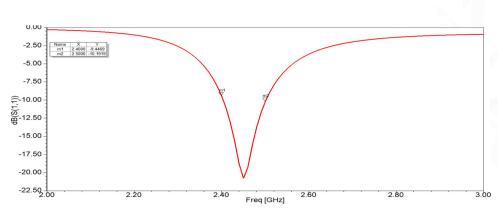
UNLESS OTHER SPECII X=± X.X=± ANGLES = ±	FIED TOLERANCES ON: X.XX= HOLEDIA = ±	PENGBANXING	深圳市朋伴兴业科技有	限公司
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PE		
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED. THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS (
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE: CHIP2450-1608 Specification		DOCUMENT	1608	SPEC REV.
TITLE: CHIP2450-1608 Specification		l NO.	1000	D4

Electrical Characteristics

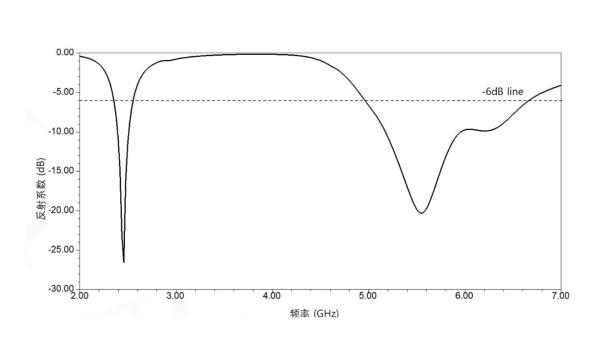
	Feature	Specification
1	Central frequency	2.45GHz
2	Bandwidth	>150MHz
3	Peak gain	2.78 dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves

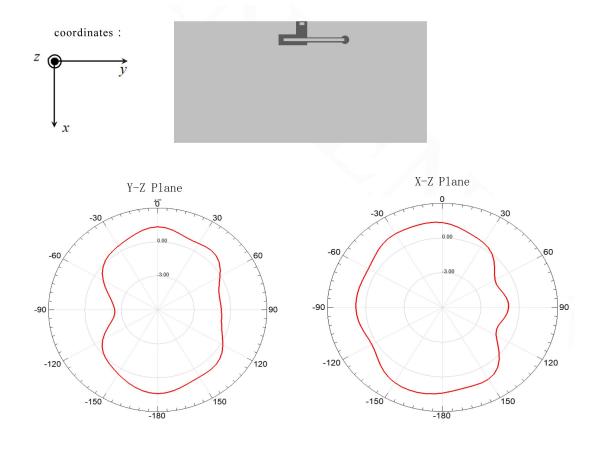




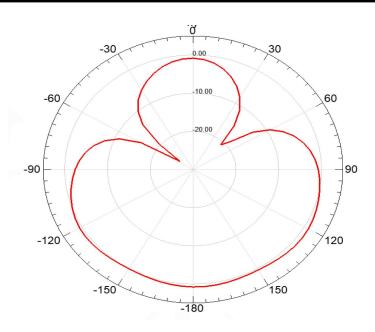
L				
UNLESS OTHER SPEC X=± X.X=± ANGLES = ±	FIED TOLERANCES ON: X.XX= HOLEDIA = ±	PENGBANXING	深圳市朋伴兴业科技有	限公司
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PB)		
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS		
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE CHIP2450 1609 Specification		DOCUMENT	1608	SPEC REV.
TITLE: CHIP2450-1608 Specification		NO.	1000	P1



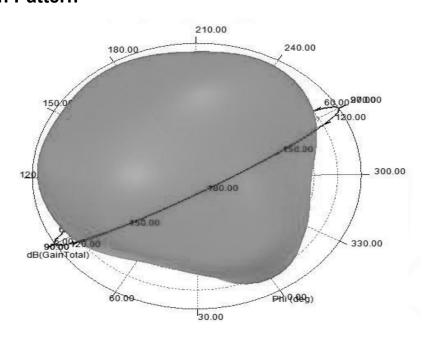
Radiation Pattern



UNLESS OTHER SPECI	FIED TOLERANCES ON:	₽ ₺ 深圳市朋伴兴业科技有		-78 /3 - 3
$X=\pm$ $X.X=\pm$	X.XX =	and the same of th	深圳巾朋件兴业科技凭	11%公司
$ANGLES = \pm$	$HOLEDIA = \pm$	PENGBANXING		
SCALE: N/A	UNIT: mm		S AND SPECIFICATIONS ARE THE PROPER	-
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED. THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS (
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
TITLE. CHIP2450-1608	Specification	1608		SPEC REV.
TITLE: CHIP2450-1608 Specification		NO.	1008	P1



3D Radiation Pattern

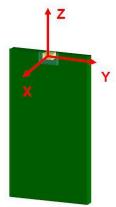


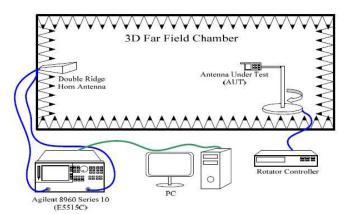
Frequency	2400MHz	2450MHz	2500MHz
Avg. gain	-1.92	-1.35	-1.56
Peak gain	1.79	2.78	2.66
Efficiency	74.55	80.25	76.98

UNLESS OTHER SPECIF	TIED TOLERANCES ON:			7B /\ =1
$X=\pm$ $X.X=\pm$	X.XX =	and the same of th	深圳巾朋件兴业科技有	限公司
$ANGLES = \pm$	$HOLEDIA = \pm$	PENGBANXING		
SCALE: N/A	UNIT: mm		S AND SPECIFICATIONS ARE THE PROPER	
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited and shall not be reproduced or used A THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS O		
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOU	JT PERMISSION	
TITLE. CHIP2/150-1608 S	necification	1600		SPEC REV.
TITLE: CHIP2450-1608 Specification		NO.	1008	P1

Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator,a standard horn antenna and Vector Network Analyzer is used to collect data.





Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock		No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150°C±5°C	No apparent damage Fulfill the electrical spec. after test.
	Temperature: -40° (±5° (No apparent damage Fulfill the electrical spec. after test.
	1. Solder bath temperature : $260\pm5^{\circ}$ C 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ\!$	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}\text{C}$ and humidity should be less than 60% RH. The product should be used within 1 year from the time of delivery.

(b) On board:

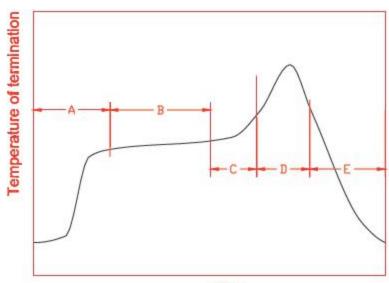
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40° C to $+105^{\circ}$ C.

UNLESS OTHER SPECIFIED TOLERANCES ON: X=± X.X=± X.XX=		pb	深圳市朋伴兴业科技有	限公司		
ANGLES = \pm	HOLEDIA = ±	PENGBANXING				
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBX				
DRAWN BY : Sera CHECKED BY: XD		TECHNOLOGY Limited and shall not be reproduced or used as the basis for the manufacture or sale of apparatus or				
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION				
TITLE: CHIP2450-1608 Specification		DOCUMENT NO.	1608	SPEC REV.		
			1008	P1		

8. Recommended Reflow Soldering



Time

Α	1 st rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140°C to 160°C	60s to 120s
С	2 nd rising temperature	Preheating to 200°C	20s to 40s
D		if 220°C	50s~60s
		if 230°C	40s∼50s
	Main heating	if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s
	2000 000		

^{*}reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

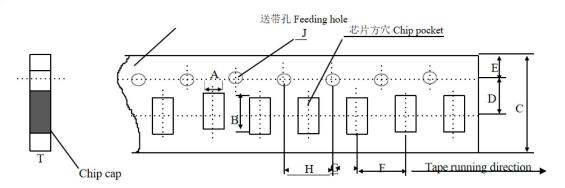
- (a) The tip temperature must be less than $350^{\circ}\,$ C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

UNLESS OTHER SPECIFIED TOLERANCES ON: X=± X.X=± X.XX=		pb	深圳市朋伴兴业科技有	i限公司				
$ANGLES = \pm$	$HOLEDIA = \pm$	PENGBANXING						
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PB						
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS				THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS		
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION						
TITLE: CHIP2450-1608 Specification		DOCUMENT NO.	1608	SPEC REV.				
			1008	P1				

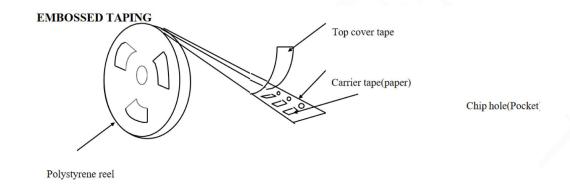
Dimensions of paper taping:



Unit: mm

代号 Code 纸带规格 papersize	A	В	С	D*	E	F	G*	Н	J	T
- t	1.10	1.90	8.00	3.50	1.75	4.00	2.00	4.00	1.50	1.10
尺寸 	±0.10	±0.10	±0.10	±0.05	±0.10	±0.10	±0.10	±0.10	-0/+0.10	Max

Reel (4000 pcs/Reel)



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature: $5\sim40^{\circ}\text{C}$ /Relative Humidity: $20\sim70\%$

UNLESS OTHER SPECIF X=± X.X=± ANGLES = ±	IED TOLERANCES ON: X.XX= HOLEDIA = ±	PENGBANXING	深圳市朋伴兴业科技有	限公司	
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PB			
DRAWN BY : Sera	CHECKED BY: XD	TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS			
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION			
TITLE: CHIP2450-1608 Specification		DOCUMENT NO.	1608	SPEC REV.	
			1008	P1	